



# Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

**Adobe Reader version 7.0.5 is required to complete this declaration.**

1752-1 1.1	IPC Web Site for Information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>	<b>Form Type *</b> Distribute	<b>Declaration Class *</b> Class 1 - RoHS Yes/No
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## Supplier Information

<b>Company Name *</b> DALSA Corporation	Company Unique ID	Unique ID Authority	<b>Response Date *</b> 2008-07-29	Response Document ID				
<b>Contact Name *</b> Mario Hurteau	Title - Contact Supv, Quality Assurance	<b>Phone - Contact *</b> 514-333-1301	<b>Email - Contact *</b> mario.hurteau@dalsa.com	Duplicate Contact -> Authorized Representative				
<b>Authorized Representative *</b> Mario Hurteau	Title - Representative Supv, Quality Assurance	<b>Phone - Representative *</b> 514-333-1301	<b>Email - Representative *</b> mario.hurteau@dalsa.com	Supplier Comments or URL for Additional Information				
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	<b>Weight *</b>	UOM	Unit Type
		Xcelera family	2008-07-29		Canada		mg	Each
Alternate Recommendation				Alternate Item Comments				

**Manufacturing Information section intentionally omitted.**

\* Required Field

Save the fields in this form to a file

Export Data

Import fields from a file into this form

Import Data

Clear all of the fields on this form

Reset Form

Lock the fields on this form to prevent changes

Lock Supplier Fields

### RoHS Material Composition Declaration

Declaration Type \*

Custom

RoHS Directive  
2002/95/EC

RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

The supplier certifies that the information provided in this form is true and correct to the best of its knowledge and belief and has used appropriate methods to ensure its accuracy. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union laws that implement RoHS Directive. Supplier proclaims that it may have relied on information provided by others in completing this form and that Supplier may not have independently verified such information. If the Company and Supplier enter into an written agreement with respect to the identified item, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

RoHS Declaration \*

4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions

Supplier Acceptance \*

Accepted

**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version

EL-2006/690/EC

+ - 5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.

+ - 6c. Lead as an alloying element in copper containing up to 4% lead by weight.

+ - 7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).

+ - 15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

### Declaration Signature

**Instructions:** Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Mario Hurteau

Digitally signed by Mario Hurteau  
DN: cn=Mario Hurteau, c=CA, o=DALSA, ou=Quality Assurance, email=mario.hurteau@dalca.com  
Date: 2008.07.31 09:20:14 -0400

**JIG section intentionally omitted.**